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ABSTRACT

A chip is bonded on a circuit board by aligning in position bumps 3 with board electrodes 5 with interposition of an anisotropic conductive layer 10 in which an insulating resin is mixed with conductive particles 10a and an inorganic filler 6f, and pressing the chip 1 against the board 4 with a pressure force of not smaller than 20 gf per bump applied to the chip 1 against the board 4 by means of a head 8 while correcting warp of the chip and the board and crushing the bumps, and hardening the insulating resin.

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